IXYS

HiPerFET™ Power MOSFETs Q-Class

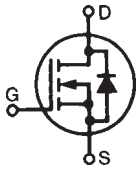
IXFK 60N55Q2
IXFX 60N55Q2

V_{DSS} = 550 V
I_{D25} = 60 A
$R_{DS(on)}$ = 88 mΩ

$t_{rr} \leq 250$ ns

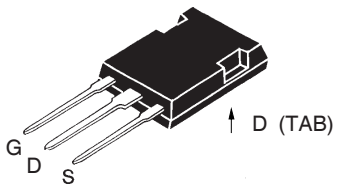
N-Channel Enhancement Mode
Avalanche Rated, High dv/dt, Low Q_g
Low intrinsic R_g, low t_{rr}

Preliminary Data Sheet

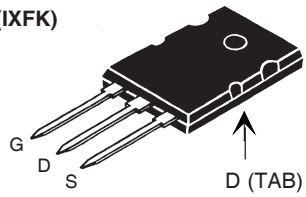


Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	550	V
V_{DGR}	T_J = 25°C to 150°C; R_{GS} = 1 MΩ	550	V
V_{GS}	Continuous	±30	V
V_{GSM}	Transient	±40	V
I_{D25}	T_C = 25°C	60	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	240	A
I_{AR}	T_C = 25°C	60	A
E_{AR}	T_C = 25°C	75	mJ
E_{AS}	T_C = 25°C	4.0	J
dv/dt	$I_S \leq I_{DM}$, di/dt ≤ 100 A/μs, $V_{DD} \leq V_{DSS}$, $T_J \leq 150°C$, R_G = 2 Ω	20	V/ns
P_D	T_C = 25°C	735	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6 mm (0.063 in) from case for 10 s	300	°C
M_d	Mounting torque TO-264	0.9/6	Nm/lb.in.
Weight	PLUS-247	6	g
	TO-264	10	g

PLUS 247™ (IXFX)



TO-264 AA (IXFK)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
V_{DSS}	V_{GS} = 0 V, I_D = 3mA	550			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8 mA	2.0		4.5	V
I_{GSS}	V_{GS} = ±30 V_{DC}, V_{DS} = 0			±200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, T_J = 25°C			50	μA
	V_{GS} = 0 V, T_J = 125°C			2	mA
$R_{DS(on)}$	V_{GS} = 10 V, $I_D = 0.5 \bullet I_{D25}$ Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			88	mΩ

Features

- Double metal process for low gate resistance
- International standard packages
- Epoxy meet UL 94 V-0, flammability classification
- Avalanche energy and current rated
- Fast intrinsic Rectifier

Advantages

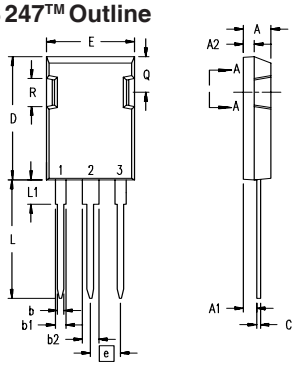
- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	min.	typ.	max.	
g_{fs}	V_{DS} = 10 V; I_D = 0.5 • I_{D25}, pulse test	30	44		S
C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		7300		pF
C_{oss}			1150		pF
C_{rss}			340		pF
$t_{d(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25} R_G = 1.0 Ω (External),		22		ns
t_r			14		ns
$t_{d(off)}$			57		ns
t_f			9		ns
$Q_{g(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		200		nC
Q_{gs}			42		nC
Q_{gd}			100		nC
R_{thJC}				0.17	K/W
R_{thCK}	TO-264		0.15		K/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	min.	typ.	max.	
I_S	V_{GS} = 0 V			60	A
I_{SM}	Repetitive; pulse width limited by T_{JM}			240	A
V_{SD}	I_F = I_S, V_{GS} = 0 V, Pulse test, t ≤ 300 µs, duty cycle d ≤ 2 %			1.5	V
t_{rr}	I_F = 25A, -di/dt = 100 A/µs, V_R = 100 V			250	ns
Q_{RM}			1		µC
I_{RM}			10		A

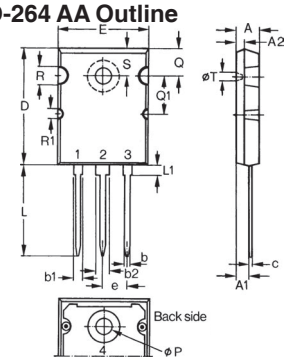
PLUS 247™ Outline



Terminals: 1 - Gate
2 - Drain (Collector)
3 - Source (Emitter)
4 - Drain (Collector)

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.83	5.21	.190	.205
A_1	2.29	2.54	.090	.100
A_2	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b_1	1.91	2.13	.075	.084
b_2	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

TO-264 AA Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.82	5.13	.190	.202
A1	2.54	2.89	.100	.114
A2	2.00	2.10	.079	.083
b	1.12	1.42	.044	.056
b1	2.39	2.69	.094	.106
b2	2.90	3.09	.114	.122
c	0.53	0.83	.021	.033
D	25.91	26.16	1.020	1.030
E	19.81	19.96	.780	.786
e	5.46 BSC		.215 BSC	
J	0.00	0.25	.000	.010
K	0.00	0.25	.000	.010
L	20.32	20.83	.800	.820
L1	2.29	2.59	.090	.102
P	3.17	3.66	.125	.144
Q	6.07	6.27	.239	.247
Q1	8.38	8.69	.330	.342
R	3.81	4.32	.150	.170
R1	1.78	2.29	.070	.090
S	6.04	6.30	.238	.248
T	1.57	1.83	.062	.072

Fig. 1. Output Characteristics @ 25°C

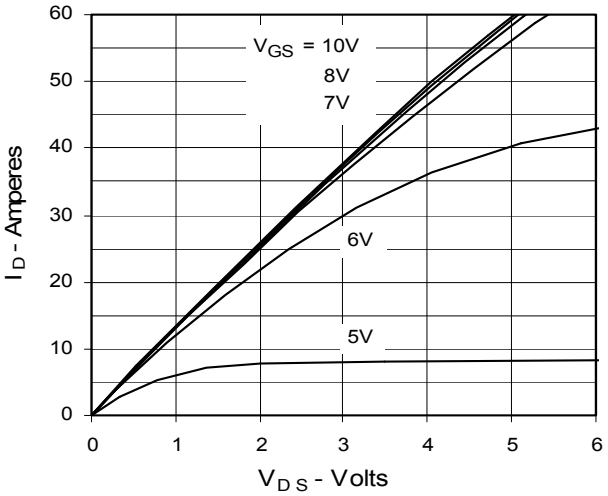


Fig. 2. Extended Output Characteristics @ 25°C

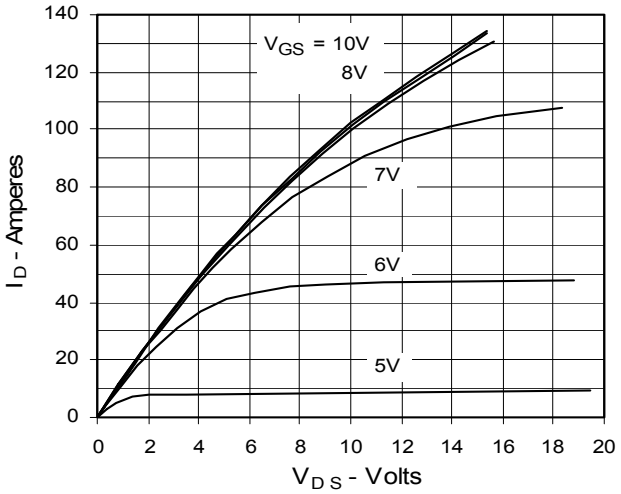


Fig. 3. Output Characteristics @ 125°C

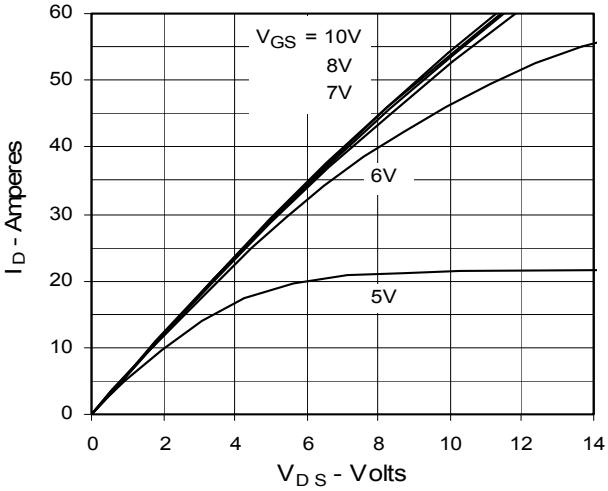


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

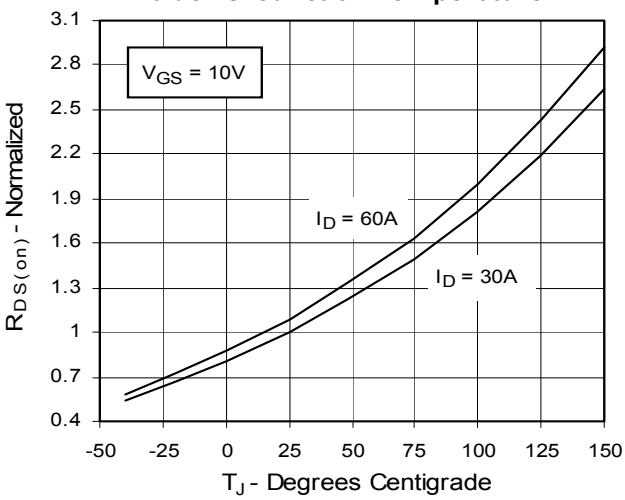


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. I_D

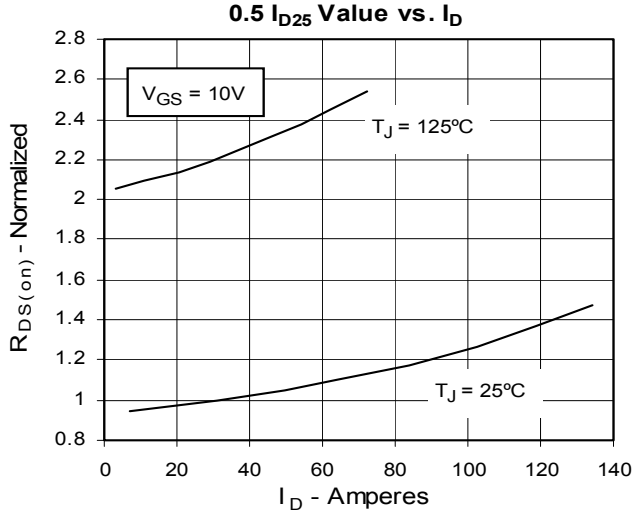


Fig. 6. Drain Current vs. Case Temperature

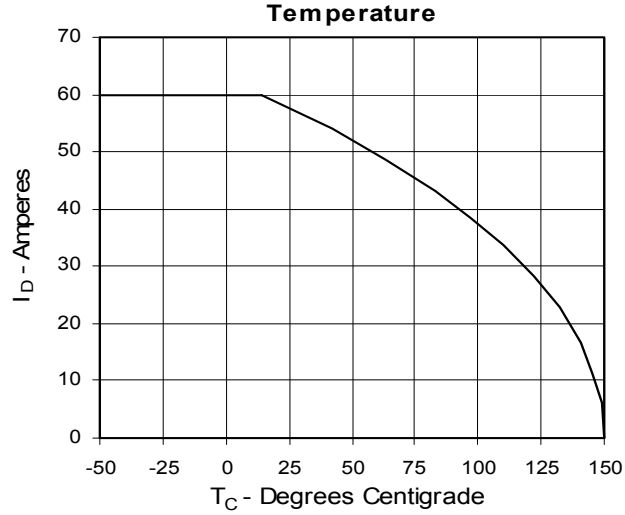


Fig. 7. Input Admittance

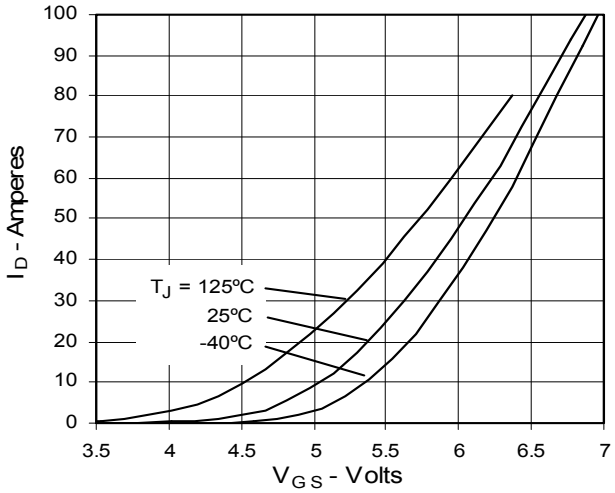


Fig. 8. Transconductance

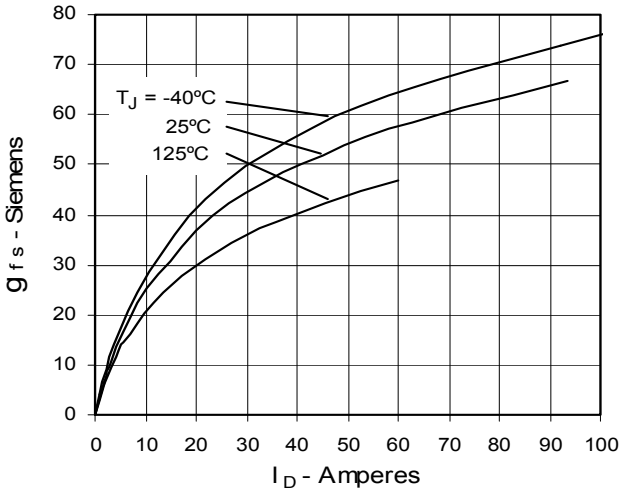


Fig. 9. Source Current vs. Source-To-Drain Voltage

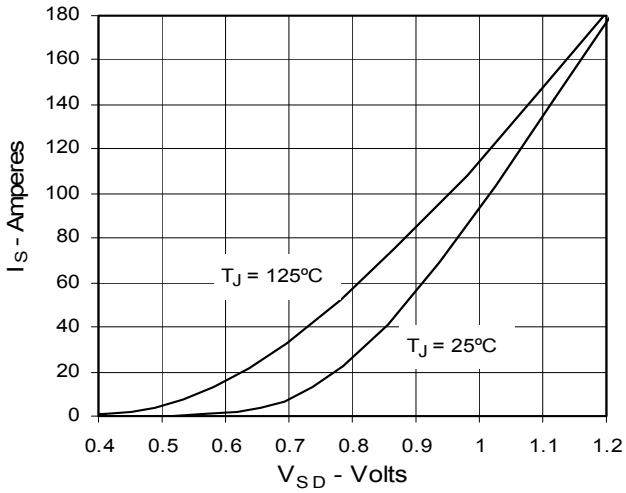


Fig. 10. Gate Charge

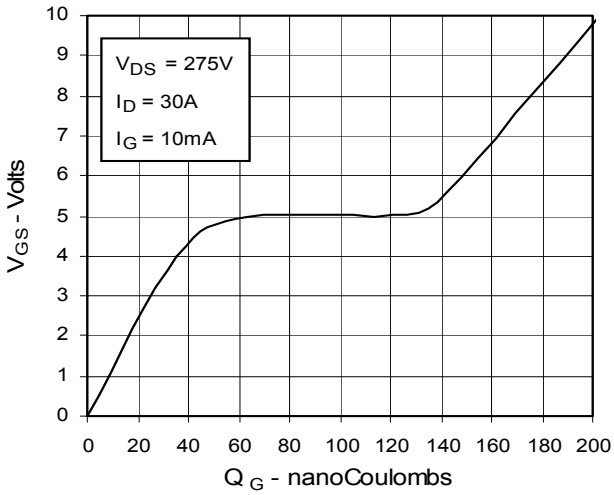


Fig. 11. Capacitance

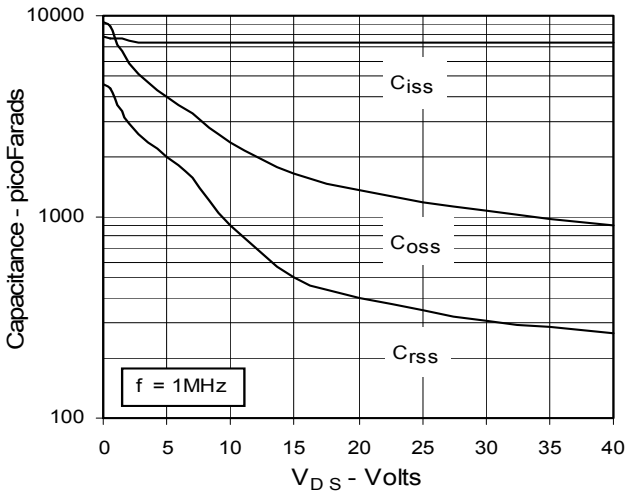


Fig. 12. Forward-Bias Safe Operating Area

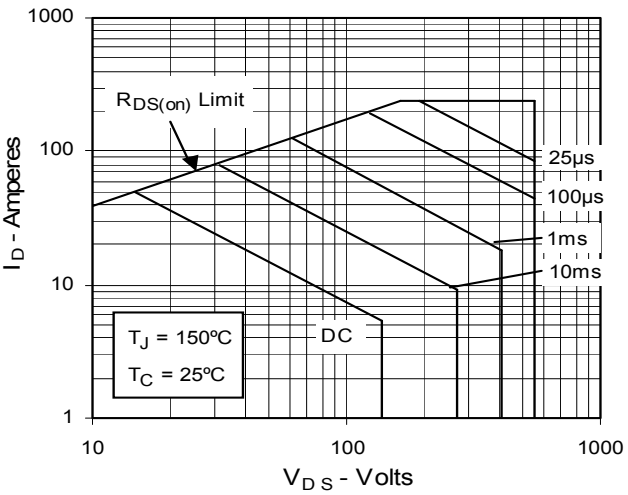


Fig. 13. Maximum Transient Thermal Resistance